

What is claimed is:

1. A stress-free lead frame (1) comprising;
 - a lead frame (10) having a plurality of integrated circuits (11), each of said plurality of integrated circuits having a die pad (12) and a plurality of leads (13); and
 - a peripheral pad (14) surrounding said lead frame (10),
 - characterised by
 - 10 said peripheral pad (14) being provided with a plurality of stress-relief means (15).
2. A stress-free lead frame (1) comprising;
 - a lead frame (10) having a plurality of integrated circuits (11), each of said plurality of integrated circuits having a die pad (12) and a plurality of leads (13); and
 - 15 a peripheral pad (14) surrounding said lead frame (10),
 - characterised by
 - 20 said peripheral pad (14) being provided with a plurality of interlocking means (16).
3. A stress-free lead frame (1) as claimed in Claim 1 further characterised by said plurality of stress-relief means (12) being holes and slots.
4. A stress-free lead frame (2) as claimed in Claim 1 further characterised by said holes and slots being arranged in multiple rows.

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5. A stress-free lead frame (3) as claimed in Claim 2 further characterised by said interlocking means (16) being a plurality of slots.

6. A stress-free lead frame (1) as claimed in Claim 4 or Claim 5 further characterised by said holes and slots are arranged side by side at equal intervals.

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